

Title (en)
METHODS OF MAKING HIERARCHICAL ARTICLES

Title (de)
VERFAHREN ZUR HERSTELLUNG VON HIERARCHISCHEN ARTIKELN

Title (fr)
PROCÉDÉS DE FABRICATION D'ARTICLES HIÉRARCHIQUES

Publication
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Application
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Priority

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Abstract (en)
[origin: WO2009002644A2] Provided is a method of fabricating hierarchical articles that contain nano features and microstructures. The method includes providing a substrate that includes nano features and then creating microstructures adding a layer, removing at least a portion of the layer to reveal at least a portion of the substrate. Also provided is a method of making hierarchical structures that contain nanofeatures and microstructures wherein the method includes adding the nanofeatures to existing microstructures using nanoparticles as an etch mask.

IPC 8 full level
B82B 3/00 (2006.01); **G03F 7/26** (2006.01); **H01L 21/02** (2006.01)

CPC (source: EP)
B81C 99/009 (2013.01); **B82Y 10/00** (2013.01); **B82Y 40/00** (2013.01); **G03F 7/0002** (2013.01); **B81B 2203/0361** (2013.01)

Citation (search report)

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- [Y] TORMEN MASSIMO ET AL: "Fabrication of three-dimensional stamps for embossing techniques by lithographically controlled isotropic wet etching", JOURNAL OF VACUUM SCIENCE AND TECHNOLOGY: PART B, AVS / AIP, MELVILLE, NEW YORK, NY, US, vol. 23, no. 6, 2 December 2005 (2005-12-02), pages 2920 - 2924, XP012080280, ISSN: 1071-1023, DOI: 10.1116/1.2130348
- See references of WO 2009002644A2

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